



# M T B F (E I A J R C R - 9 1 0 2 B)

Model	G1W-12
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No.	Parts		Q'ty of Device	Failure rate [10 <sup>-6</sup> /H]	Reference
1	IC	Linear	4	0.0960	
2	Transistors	NPN/PNP	0	0.0000	
3	Transistors	Power NPN/PNP	2	0.0840	
4	FET	MOS FET	2	0.1980	
5	Diodes	FR	4	0.0880	
6	Diodes	Zener	2	0.0480	
7	Diodes	bridge	4	0.2640	
8	Resistors	Metal Film	32	0.5120	
9	Resistors	Power Film	6	0.2460	
10	Resistors	variable	2	0.0320	
11	Capacitors	Aluminum Electrolytic	10	0.1900	
12	Capacitors	Film	6	0.0504	
13	Transformer	Power	1	0.3600	
14	Fuses		3	0.0600	
15	Connectors	Printed Crcuit Board	8	0.4160	
16	Connection	Hand Solder	11	0.0286	
17	Connection	Flow Solder	286	0.1487	
18	Connection	Crimp	32	0.0198	
19	Connection	Screw	5	0.0050	
20	Printed Crcuit Board	Through Hole	2	0.0900	
Total Failure Rate [10 <sup>-6</sup> /H]				2.9366	

M T B F	[H]	340,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-